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Sheet 1 of 1

Form 1449*

INFORMATION DISCLOSURE STATEMENT
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(Use several sheets if necessary)

Atty. Docket No.: 303.691US1

Serial No. 09/584,566

Applicant: Leonard Forbes et al.

Filing Date: May 31, 2000

Group: 2818

U.S. PATENT DOCUMENTS

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Sheet 1 of 2

Form 1449*

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^{**}EXAMINER: Initial a citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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